12N50-CB Preliminary Power MOSFET

12A, 500V N-CHANNEL POWER MOSFET

■ DESCRIPTION

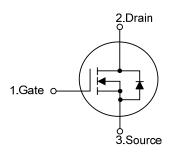
The UTC **12N50-CB** is a N-channel mode power MOSFET using UTC's advanced technology to provide customers with planar stripe and DMOS technology. This technology allows a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The UTC **12N50-CB** is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.



- * $R_{DS(ON)} \le 0.52\Omega$ @ $V_{GS}=10V$, $I_D=6.0A$
- * High Switching Speed
- * 100% Avalanche Tested

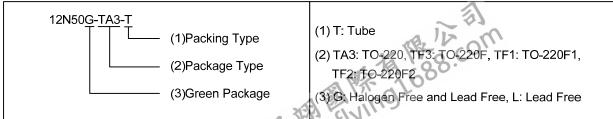


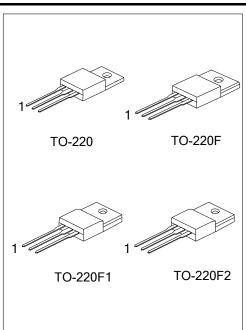


ORDERING INFORMATION

Ordering Number		Daakaga	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
12N50L-TA3-T	12N50G-TA3-T	TO-220	G	D	S	Tube	
12N50L-TF1-T	12N50G-TF1-T	TO-220F1	G	D	S	Tube	
12N50L-TF2-T	12N50G-TF2-T	TO-220F2	G	D	S	Tube	
12N50L-TF3-T	12N50G-TF3-T	TO-220F	G	D	S	Tube	

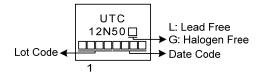
Note: Pin Assignment: G: Gate D: Drain S: Source





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MARKING





■ ABSOLUTE MAXIMUM RATINGS (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		$V_{ m DSS}$	500	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Drain Current	Continuous	I _D 12		Α	
	Pulsed (Note 2)	I _{DM}	48	Α	
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	115	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	3.5	V/ns	
Power Dissipation	TO-220		160	W	
	TO-220F/TO-220F1	P_D	50	W	
	TO-220F2		54	W	
Junction Temperature		T_J	+150	°C	
Storage Temperature		T _{STG}	-55 ~ + 150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L =10mH, I_{AS} = 4.8A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 4. $I_{SD} \le 12A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

■ THERMAL DATA

PARAMETER	PACKAGE	SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/TO-220F TO-220F1/TO-220F2	θ_{JA}	62.5	°C/W
Junction to Case	TO-220		0.78	°C/W
	TO-220F/TO-220F1	θ_{JC}	2.5	°C/W
	TO-220F2		2.31	°C/W



■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	I _D =250μA, V _{GS} =0V	500			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			10	μΑ
Gate- Source Leakage Current	Forward		V _{GS} =+30V, V _{DS} =0V			+100	nA
	Reverse	I _{GSS}	V_{GS} =-30V, V_{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =6.0A			0.52	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C_{ISS}			1360		pF
Output Capacitance		Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		150		pF
Reverse Transfer Capacitance		C_{RSS}			6		pF
SWITCHING PARAMETERS							
Total Gate Charge (Note 1)		Q_G	V _{DS} =50V, V _{GS} =10V, I _D =1.3A		86		nC
Gate to Source Charge		Q_GS	I_{G} =100µA (Note 1, 2)		9		nC
Gate to Drain Charge		Q_GD	IG-100μΑ (Note 1, 2)		8		nC
Turn-ON Delay Time (Note 1)		t _{D(ON)}			60		ns
Rise Time		t_R	V_{DD} =30V, V_{GS} =10V, I_{D}		48		ns
Turn-OFF Delay Time		t _{D(OFF)}	=0.5A, R _G =25Ω (Note 1, 2)		260		ns
Fall-Time		t_{F}			56		ns
SOURCE- DRAIN DIODE RATIN	NGS AND CH	ARACTERIST	TICS				
Maximum Body-Diode Continuous Current		I _S				12	Α
Maximum Body-Diode Pulsed Current		I _{SM}				48	Α
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I _S =12A, V _{GS} =0V			1.4	V
Reverse Recovery Time (Note 1))	t _{rr}	I _S =12A, V _{GS} =0V		250		ns
Reverse Recovery Charge		Q_{rr}	dI _F /dt=100A/μs		3		μC

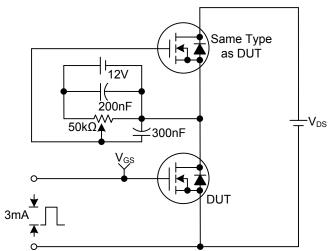
Notes: 1. Pulse Test: Pulse width \leq 300 μ s, Duty cycle \leq 2%.



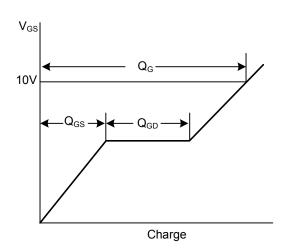
^{2.} Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

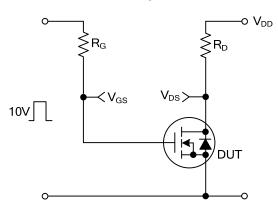
Gate Charge Test Circuit



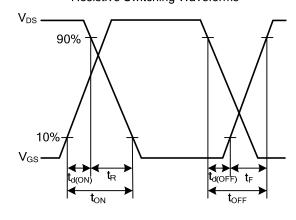
Gate Charge Waveforms



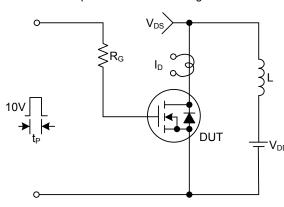
Resistive Switching Test Circuit



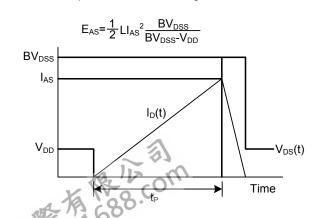
Resistive Switching Waveforms



Unclamped Inductive Switching Test Circuit

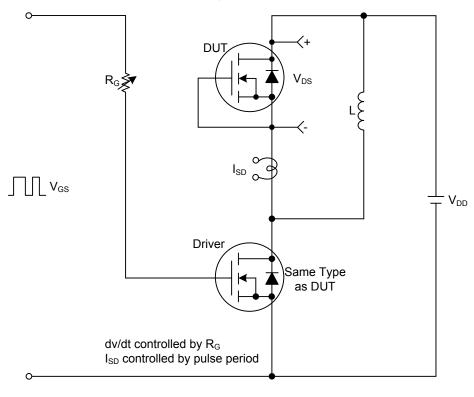


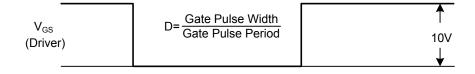
Unclamped Inductive Switching Waveforms

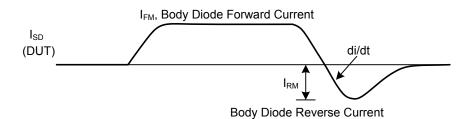


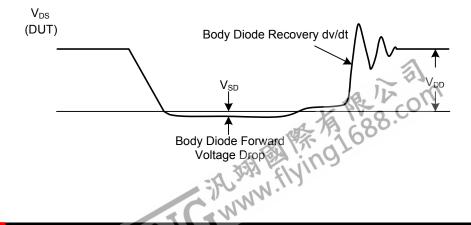
■ TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms









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